

Tyrone Camarero Specifications



Camarero SDI100C3S-436H

Key features

Enterprise Server, iSCSI SAN, HPC, Data Center, Database Processing & Storage, Corporate Database

- Dual Socket P+ (LG-4189), 3rd Gen Intel® Xeon® Scalable processors, Support CPU TDP 120-270W
- Intel® C621A
- Memory Capacity: 16 DIMM slots, UP to 4TB: 16x 256 GB DRAM, Memory Type: 3200MHz ECC DDR4, RDIMM; LRDIMM; DCPMM
- 2x 10Gbe, Server remote management: IPMI 2.0 / KVM over LAN / Media over LAN per node
- 36 3.5"/2.5" Hot-swap SAS3/SATA3 drives (4 Hybrid NVMe), 2x Rear SATA Slots, 1x SATA/NVMe M.2 (form factor: 2280 and 22110)
- 7x 8cm hot-swap counter-rotate redundant PWM cooling fans
- 1600W Redundant Power Supplies Titanium Level (96%)
- HW RAID support via Broadcom® 3908



Processor/Cache	Front Panel
Processor: Dual Socket P+ (LG-4189), 3rd Gen Intel® Xeon® Scalable processors, Support CPU TDP 120-270W	LEDs: HDD activity, Network activity, Power status, System information (overheat/UID)
Chipset: Intel® C621A	Buttons: Power On/Off
System Memory	Drive Bays
Memory Capacity: 16 DIMM slots, UP to 4TB: 16x 256 GB DRAM, Memory Type: 3200MHz ECC DDR4, RDIMM; LRDIMM; DCPMM	HDD Bays: 36x 3.5" hot-swap SATA3/SAS3 drive bays (4x 3.5" NVMe hybrid), 1 M.2 NVMe
Expansion Slots	Power Supply
PCI-Express: Slot 1: PCI-E 4.0 x8 LP, Slot 2: PCI-E 4.0 x16 LP, Slot 3: PCI-E 4.0 x16 LP, Slot 4: PCI-E 4.0 x16 LP, Slot 5: PCI-E 4.0 x16 LP, Slot 6: PCI-E 4.0 x8 LP Note: PCIe slot 1/2 is occupied by the JBOD Expansion/Storage Controller	1600W Redundant Power Supplies Titanium Level (96%)
Integrated Onboard	Cooling System
Network Connectivity: 2x 10GbE BaseT with Intel® X550 LAN: 1 RJ45 Dedicated IPMI LAN port SATA: Intel® C621A controller for 14 SATA3 (6 Gbps) ports; RAID 0,1,5,10	7 Heavy Duty 8cm Fan(s)
Add-on Options	Form Factor
Raid Card: Optional Optical Drive: None	Form Factor: 4U Rackmount Dimensions: Height: 7", Width: 17.2", Depth: 27.5"
Email : info@tyronesystems.com For more/current product information, visit www.tyronesystems.com	

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